

March 7, 2024

Participants in the ISES Japan Summit Visit Resonac's Semiconductor Backend Process R&D Base

— Semiconductor companies' executives and leaders of academia and research institutions visited Resonac's Packaging Solution Center —

Resonac Corporation (President: Hidehito Takahashi, hereinafter "Resonac") conducted a tour of its Packaging Solution Center (Kawasaki City, Kanagawa Prefecture, hereinafter referred to as "PSC"), an R&D facility of backend process of semiconductor manufacturing, for 20 people, who were executives of semiconductor companies and leaders of academic societies and research institutions coming from US and European countries and taking part in the International Semiconductor Executive Summit (ISES) Japan Summit 2024 held in Tokyo from March 5th to 6th. There were 150 participants in the ISES in total. PSC is an open innovation base for materials used in backend process, packaging and evaluation technologies, equipped with a full lineup of manufacturing equipment for advanced semiconductor packages. It is rare for a semiconductor material company to have such a base.

ISES is a summit meeting attended by executives and leaders of major semiconductor companies, equipment and material manufacturers, and academic societies and research institutions. Since 2010, it has been holding events in major regions such as the United States, Europe and Taiwan, and occupies an important position that influences industry trends and decisions as a platform for information exchange, strategy, and discussions on the direction of the semiconductor industry. This time, it was held in Japan for the first time, and executives of the Ministry of Economy, Trade and Industry and leading semiconductor manufacturers including Intel, TSMC, Samsung and AMD gave lectures in the event.

In recent years, with the rapid expansion of generative AI, further evolution of AI semiconductors is required, and semiconductor backend process technologies including 2.xD and 3D* package technologies, materials and manufacturing equipment are attracting attention of semiconductor industry stakeholders all over the world. In addition, the cutting-edge backend process materials and manufacturing equipment are areas where Japanese manufacturers lead the world. This time, the participants of the ISES Japan Summit considered it a valuable opportunity to visit the PSC, which is equipped with Japan's cutting-edge backend process materials and manufacturing equipment, and see 2.xD, 3D packages and their manufacturing equipment, and took part in the tour after the end of the second day of the summit meeting.

Resonac will continue to actively utilize the PSC to work on research and development of next-generation semiconductor package materials and evaluation/implementation technologies, and accelerate co-creation with other companies.

[About the Packaging Solution Center]

The PSC is the unique facility of material company that has a full lineup of manufacturing equipment for advanced semiconductor packages (including dicing-saw to cut wafers, equipment for chip mounting, molding, inspection and evaluation), and is a base for open innovation, research and development of backend process materials and evaluation/implementation technologies. The consortium "JOINT2", which consists of 14

semiconductor-related companies and is established by Resonac, is also based at the PSC.

*2.5D is a technology that arranges IC chips in parallel on an interposer. 3D is a technology that stacks chips using TSV (Through-Silicon Via).

[About the Resonac Group]

The Resonac Group is a group of chemical companies that produces and sells products related to semiconductor and electronic materials, mobility, innovation enabling materials, chemicals, etc. The Group has a wide variety of materials and advanced material technologies applicable to midstream to downstream of supply chains of various products. In January 2023, the Showa Denko Group and the Showa Denko Materials Group (former Hitachi Chemical Group) merged into the Resonac Group and made a start as a new corporate group. The new trade name “RESONAC” was created as a combination of two English words, namely, the word of “RESONATE” and “C” as the first letter of CHEMISTRY. As a “co-creative chemical company,” Resonac aims to continue growing and enhance its corporate value through co-creation. The Group recorded net sales of about 1,400 billion yen in 2022, and its overseas sales accounted for 56% of net sales. The Group has deployed production/sales bases in 22 countries and regions, and continues operating its business globally (as of January 2023).

For detail, please refer to our Website.

Resonac Holdings Corporation: <https://www.resonac.com/>

For further information, contact:

Public Relations Group, Brand Communication Department (Phone: 81-3-6263-8002)
Resonac Holdings Corporation